



Material Content Data Sheet



Sales Product Name		IPD60R460CE		Issued		24. January 2018		
MA#		MA001704956						
Package		PG-TO252-3-344		Weight*		323.64 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.072	1.26	1.26	12581	12581
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		134	
	non noble metal	iron	7439-89-6	0.144	0.04		445	
	non noble metal	copper	7440-50-8	143.904	44.48	44.53	444641	445220
	non noble metal	aluminium	7429-90-5	0.446	0.14	0.14	1377	1377
wire	non noble metal	aluminium	7429-90-5	0.446	0.14	0.14	1377	1377
encapsulation	organic material	carbon black	1333-86-4	0.674	0.21		2081	
	plastics	epoxy resin	-	18.187	5.62		56197	
	inorganic material	silicondioxide	60676-86-0	115.861	35.80	41.63	357993	416271
leadfinish	non noble metal	tin	7440-31-5	3.834	1.18	1.18	11845	11845
solder	non noble metal	tin	7440-31-5	0.069	0.02		212	
	noble metal	silver	7440-22-4	0.086	0.03		266	
	non noble metal	lead	7439-92-1	3.284	1.01	1.06	10147	10625
heatspreader	inorganic material	phosphorus	7723-14-0	0.010	0.00		31	
	non noble metal	iron	7439-89-6	0.033	0.01		102	
	non noble metal	copper	7440-50-8	32.995	10.19	10.20	101948	102081
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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